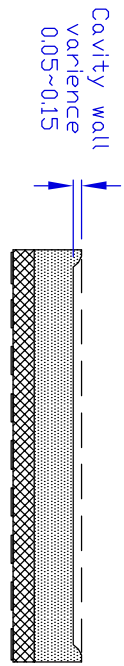
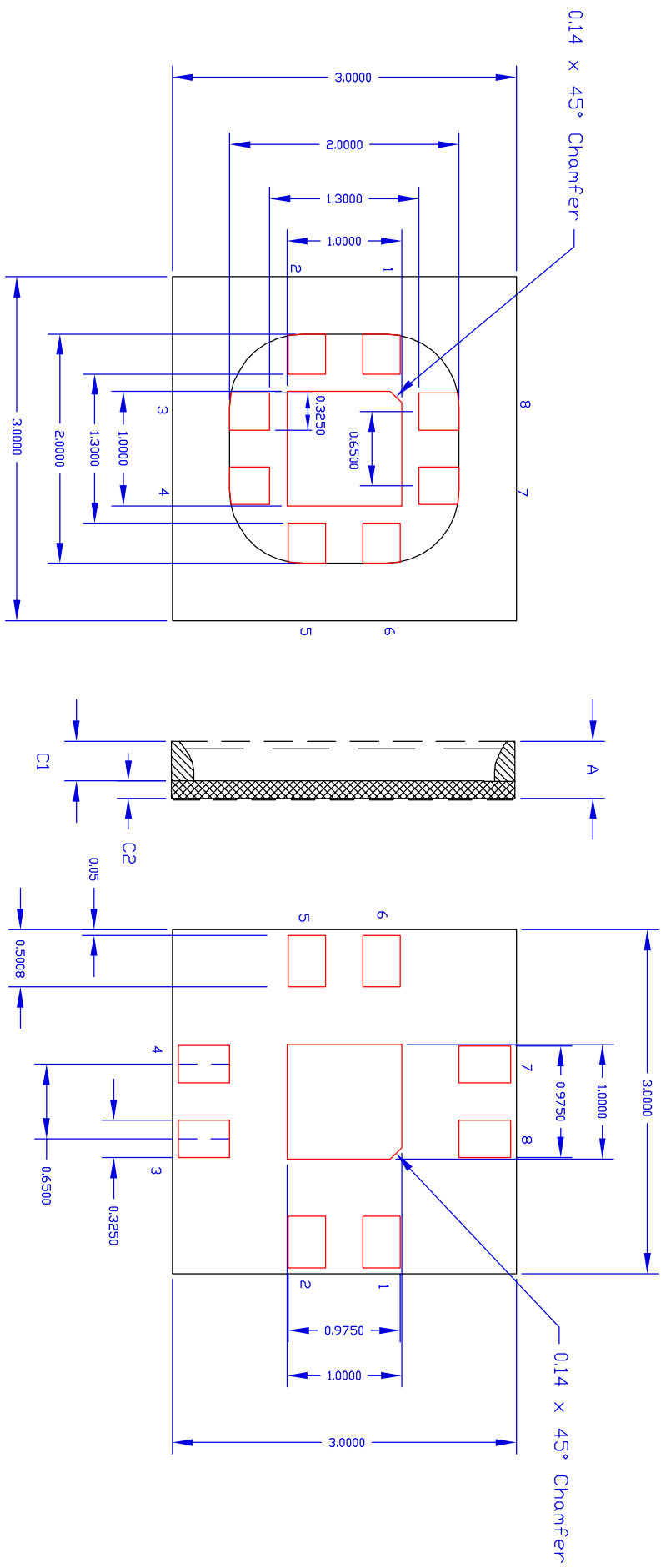


TOP VIEW SIDE VIEW BOTTOM VIEW

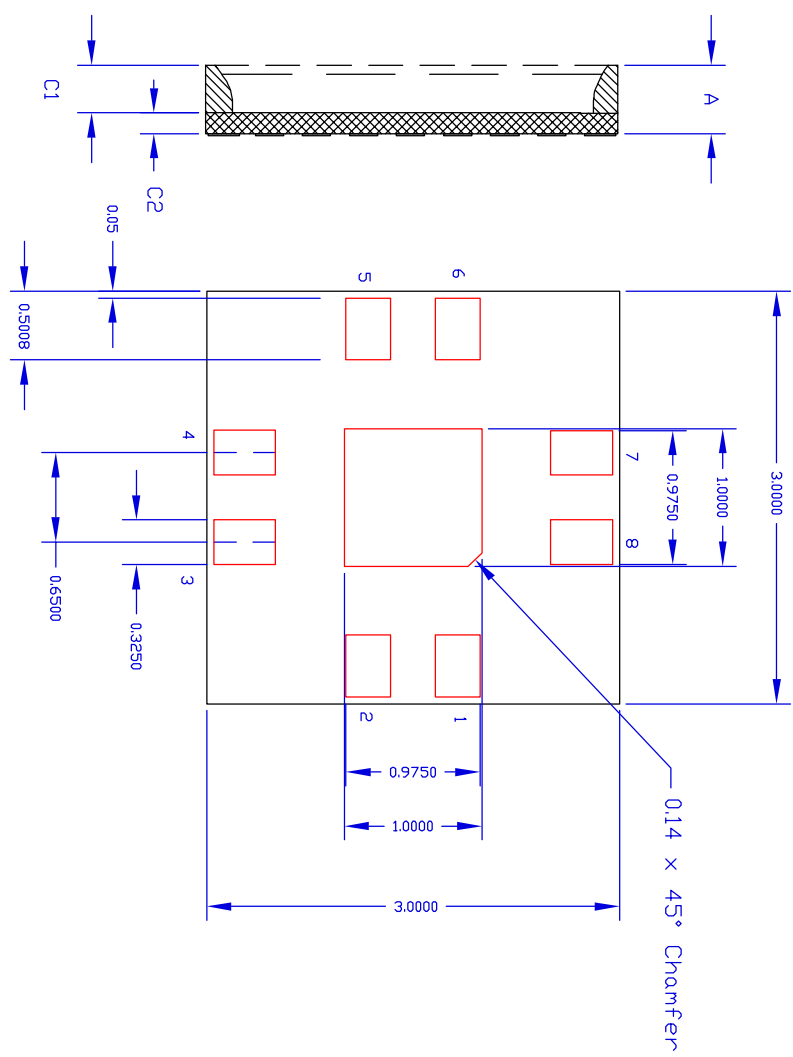


SIDE VIEW

HEIGHT TABLE			
SERIES	C1	C2	A
A-QFN	0.63	0.27	0.90
A-TQFN	0.38	0.27	0.65
TDL	+/-	+/- 0.10	+/- 0.05

OTHER SIZES AVAILABLE

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Note:

1. Organic substrate
2. Cavity Dam: Hysol FP4451TD
3. Pads: Cu/Ni/Au
4. Copper Thickness: 12µm~18µm (0.5~0.7mil)
5. Bonding Pad Gold Thickness: 1.3µm (50 micro-inch)
6. PCB Pads Gold Thickness: 0.13µm (5 micro-inch)
7. Nickel Thickness: 3.8µm (150 micro-inch)
8. All Dimensions Are mm

TOLERANCES UNLESS NOTED:		APPROVALS		DATE	
X.XXX	±	DRAWN TA		11/29/08	
X.XXX	±				
X.XXX	±				
ANGLES ±		ENG		TITLE	
ALL DIMENSIONS ARE IN: <input type="checkbox"/> MILLIMETERS <input type="checkbox"/> INCHES		MFG		8-LEAD 3MM P=0.65MM A-QFN (AIR) OPEN CAVITY	
THIRD ANGLE PROJECTION:		SCALE		SIZE	
		NONE		A	
DRAWING NO. 460810		DRAWING NO. 460810		REV A	
DO NOT SCALE DRAWING		SHEET 1 OF 1			

